508475985 04/03/2024

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Guangze PAN,	03/20/2024
Dan LI,	03/20/2024
Bochen CHEN,	03/20/2024
Lijun SUN,	03/20/2024
Yuanhang WANG,	03/20/2024
Wenwei LIU,	03/20/2024
Jianfeng YANG	03/20/2024
Xiaojian DING,	03/20/2024

### **RECEIVING PARTY DATA**

Company Name:	CHINA ELECTRONIC PRODUCT RELIABILITY AND ENVIRONMENTAL TESTING RESEARCH INSTITUTE (THE FIFTH ELECTRONIC RESEARCH INSTITUTE OF MINISTRY OF INDUSTRY AND INFORMATION TECHNOLOGY) (CEPREI)
Street Address:	No. 78, West Zhucun Avenue
Internal Address:	Zhucun Street, Zengcheng District
City:	Guangzhou
State/Country:	CHINA
Postal Code:	511370

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	18625748

### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 6026184576

Email: pat-dept@quarles.com,cheryl.clark@quarles.com

**QUARLES & BRADY LLP Correspondent Name:** 411 East Wisconsin Avenue Address Line 1: Address Line 4: Milwaulkee, WISCONSIN 53202

> **PATENT** REEL: 066995 FRAME: 0710

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ATTORNEY DOCKET NUMBER:	195902.00083	
NAME OF SUBMITTER:	Cheryl Clark	
SIGNATURE:	Cheryl Clark	
DATE SIGNED:	04/03/2024	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

## **Total Attachments: 3**

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> PATENT REEL: 066995 FRAME: 0711

#### **ASSIGNMENT**

WHEREAS, I (we), Guangze PAN, Dan LI, Bochen CHEN, Lijun SUN, Yuanhang WANG, Wenwei LIU, Jianfeng YANG and Xiaojian DING, all of Guangzhou, China, (singly, or collectively referred to as "ASSIGNOR"), have invented a certain invention entitled

# METHOD AND APPARATUS FOR PROCESSING ACCELERATED TEST DATA BASED ON MULTIPLE PERFORMANCE DEGRADATION, AND COMPUTER DEVICE

as set forth in this United States Patent Application or International Patent Application,

X	executed concurrently herewith
	executed on
	Serial No.

WHEREAS, CHINA ELECTRONIC PRODUCT RELIABILITY AND ENVIRONMENTAL TESTING RESEARCH INSTITUTE ( (THE FIFTH ELECTRONIC RESEARCH INSTITUTE OF MINISTRY OF INDUSTRY AND INFORMATION TECHNOLOGY) (CEPREI) ), a corporation of Guangdong, China, having its principal place of business at No. 78, West Zhucun Avenue, Zhucun Street, Zengcheng District, Guangzhou, Guangdong 511370 China. (hereinafter referred to as "ASSIGNEE"), desires to acquire or otherwise obtain the entire right, title, and interest in and to said inventions, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below;

NOW THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNOR has sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the full and exclusive right, title, and interest throughout the world in and to (a) the above-identified invention or inventions and all improvements and modifications thereof, (b) the above-identified application and all other applications for Letters Patent of the United States and countries foreign thereto for the above-identified invention or inventions and all improvements and modifications thereof, (c) all Letters Patent which may issue from said applications in the United States and countries foreign thereto, (d) all divisions, continuations, reissues, and extensions of said applications and Letters Patent, and (e) the right to claim for any of said applications the full benefits and priority rights under the International Convention and any other international agreement to which the United States adheres; such right, title, and interest to be held and enjoyed by ASSIGNEE, its successors and assigns, to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by ASSIGNOR had this Assignment not been made.

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any country, or any treaty/union organization, and all divisional applications, renewal applications, confirmation applications, validation applications, utility model applications and design applications thereof, and all reissues, renewals, reexaminations, and extensions thereof;

ASSIGNOR HEREBY AUTHORIZES AND REQUESTS the Commissioner of any official of any country, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY authorize the above-mentioned ASSIGNEE or its legal representative to insert in this instrument the filing date and serial number of said Application or any other information that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or countries foreign to the United States;

ASSIGNOR HEREBY AGREES (a) to communicate to ASSIGNEE, its successors and assigns, or their representatives or agents, all facts and information known or available to ASSIGNOR respecting said invention or inventions, improvements, and modifications including evidence for interference, reexamination, reissue, opposition, revocation, extension, or infringement purposes or other legal, judicial, or administrative proceedings, whenever requested by ASSIGNEE; (b) to testify in person or by affidavit as required by ASSIGNEE, its successors and assigns, in any such proceeding in the United States or a country foreign thereto; (c) to execute and deliver, upon request by ASSIGNEE, all lawful papers including, but not limited to, original, divisional, continuation, and reissue applications, renewals, assignments, powers of attorney, oaths, affidavits, declarations, depositions; and (d) to provide all reasonable assistance to ASSIGNEE, its successors and assigns, in obtaining and enforcing proper title in and protection for said invention or inventions, improvements, and modifications under the intellectual property laws of the United States and countries foreign thereto.

ASSIGNOR HEREBY REPRESENTS AND WARRANTS that ASSIGNOR has the full and unencumbered right to sell, assign, convey, and transfer the interests sold, assigned, and transferred herein, and that ASSIGNOR has not executed and will not execute any document or instrument in conflict herewith.

Guangze PAN	Signature of ASSIGNOR	2024.2.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing
Dan LI	Dan Li	2024.3.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing
Bochen CHEN	Bochen CHEN	2024 · 3 · 20
(type name of Assignor)	Signature of ASSIGNOR	date of signing
Lijun SUN	Lijun SUN	2024.3.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing
Yuanhang WANG	Yuanhang WAVG	2014.3.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing
Wenwei LIU	Wenner Cin	2024.3.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing

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Jianfeng YANG	Jian feng YANG	2024.3.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing
Xiaojian DING	Xiaojian DING	2024.3.20
(type name of Assignor)	Signature of ASSIGNOR	date of signing

**RECORDED: 04/03/2024**